



08N50-CB

Power MOSFET

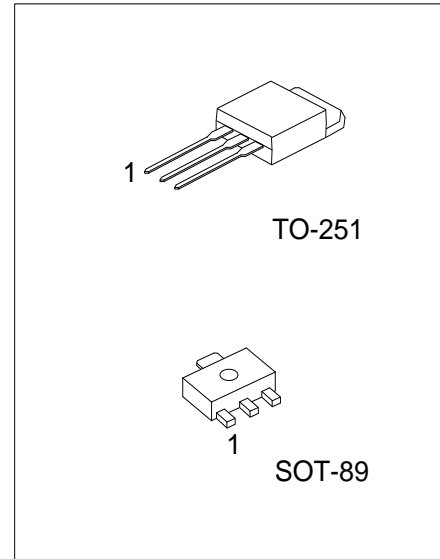
0.8A, 500V N-CHANNEL POWER MOSFET

DESCRIPTION

The UTC 08N50-CB is a high voltage MOSFET and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and have a high rugged avalanche characteristics. This power MOSFET is usually used at high speed switching applications in power supplies, PWM motor controls, high efficient DC to DC converters and bridge circuits.

FEATURES

- * $R_{DS(on)} \leq 12\Omega @ V_{GS}=10V, I_D=0.4A$
- * High breakdown voltage



ORDERING INFORMATION

Ordering Number		Package	Pin Assignment			Packing
Lead Free	Halogen Free		1	2	3	
08N50L-AB3-R	08N50G-AB3-R	SOT-89	G	D	S	Tape Reel
08N50L-TM3-T	08N50G-TM3-T	TO-251	G	D	S	Tube

Note: Pin Assignment: G: Gate D: Drain S: Source

<p>08N50G-AB3-R</p> <p>(1) Packing Type (2) Package Type (3) Green Package</p>	<p>(1) R: Tape Reel, T: Tube (2) AB3: SOT-89, TM3: TO-251 (3) G: Halogen Free and Lead Free, L: Lead Free</p>
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MARKING

SOT-89	TO-251
<p>Lot Code Date Code L: Lead Free G: Halogen Free</p>	<p>Lot Code Date Code L: Lead Free G: Halogen Free</p>



■ **ABSOLUTE MAXIMUM RATINGS** ($T_C = 25^\circ\text{C}$, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V_{DSS}	500	V
Gate-Source Voltage		V_{GSS}	± 30	V
Drain Current	Continuous	I_D	0.8	A
	Pulsed (Note 2)	I_{DM}	3.2	A
Avalanche Energy	Single Pulsed (Note 3)	E_{AS}	6.5	mJ
Peak Diode Recovery dv/dt (Note 4)		dv/dt	5.6	V/ns
Power Dissipation	SOT-89	P_D	3.3	W
	TO-251		25	W
Junction Temperature		T_J	+150	$^\circ\text{C}$
Storage Temperature Range		T_{STG}	-55 ~ +150	$^\circ\text{C}$

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Repetitive Rating : Pulse width limited by maximum junction temperature.

3. $L = 10\text{mH}$, $I_{AS} = 1.14\text{A}$, $V_{DD} = 50\text{V}$, $R_G = 25\ \Omega$, Starting $T_J = 25^\circ\text{C}$

4. $I_{SD} \leq 1.0\text{A}$, $di/dt \leq 200\text{A}/\mu\text{s}$, $V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$

■ **THERMAL DATA**

PARAMETER		SYMBOL	RATINGS	UNIT
Junction to Ambient	SOT-89	θ_{JA}	160	$^\circ\text{C}/\text{W}$
	TO-251		110	$^\circ\text{C}/\text{W}$
Junction to Case	SOT-89	θ_{JC}	38	$^\circ\text{C}/\text{W}$
	TO-251		5	$^\circ\text{C}/\text{W}$

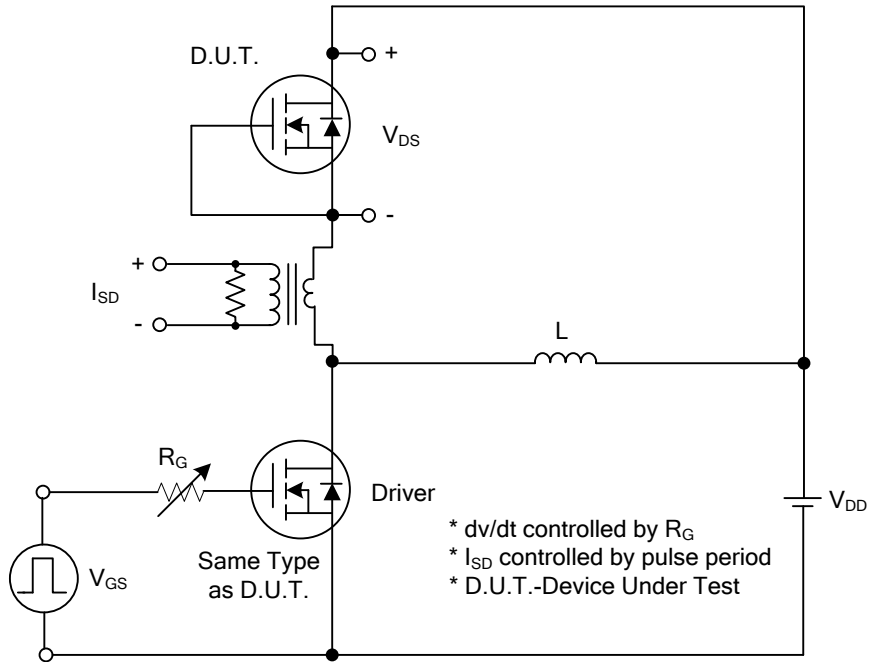
■ **ELECTRICAL CHARACTERISTICS** ($T_J = 25^\circ\text{C}$, unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	$I_D=250\mu\text{A}$, $V_{GS}=0\text{V}$	500			V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=500\text{V}$, $V_{GS}=0\text{V}$			10	μA
Gate-Source Leakage Current	Forward	I_{GSS}			+100	nA
	Reverse				-100	nA
ON CHARACTERISTICS						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$	2.0		4.0	V
Static Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=10\text{V}$, $I_D=0.4\text{A}$			12	Ω
DYNAMIC PARAMETERS						
Input Capacitance	C_{ISS}	$V_{GS}=0\text{V}$, $V_{DS}=25\text{V}$, $f=1.0\text{MHz}$		80		pF
Output Capacitance	C_{OSS}			15		pF
Reverse Transfer Capacitance	C_{RSS}			2		pF
SWITCHING PARAMETERS						
Total Gate Charge (Note 1)	Q_G	$V_{DS}=100\text{V}$, $V_{GS}=10\text{V}$, $I_D=0.8\text{A}$, $I_D=1\text{mA}$ (Note 1, 2)		6		nC
Gate to Source Charge	Q_{GS}			3.2		nC
Gate to Drain Charge	Q_{GD}			0.35		nC
Turn-ON Delay Time (Note 1)	$t_{D(ON)}$	$V_{DS}=100\text{V}$, $V_{GS}=10\text{V}$, $I_D=0.8\text{A}$, $R_G=6\Omega$ (Note 1, 2)		2.8		ns
Rise Time	t_R			16.7		ns
Turn-OFF Delay Time	$t_{D(OFF)}$			18.4		ns
Fall-Time	t_F			34		ns
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS						
Maximum Body-Diode Continuous Current	I_S				0.8	A
Maximum Body-Diode Pulsed Current	I_{SM}				3.2	A
Drain-Source Diode Forward Voltage (Note 1)	V_{SD}	$I_S=0.8\text{A}$, $V_{GS}=0\text{V}$			1.4	V
Body Diode Reverse Recovery Time (Note 1)	t_{rr}	$I_S=1.0\text{A}$, $V_{GS}=0\text{V}$, $dI_F/dt = 100\text{A}/\mu\text{s}$		146		ns
Body Diode Reverse Recovery Charge	Q_{rr}			265		nC

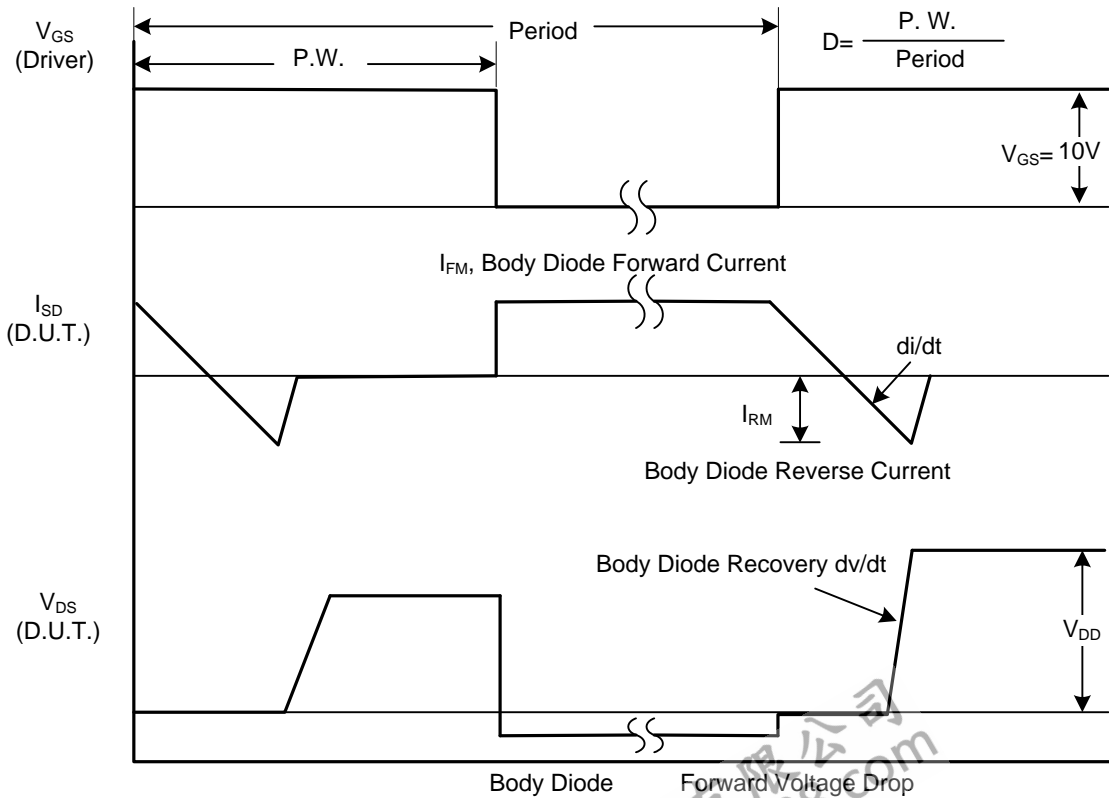
Notes: 1. Pulse Test: Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$.

2. Essentially independent of operating temperature.

■ TEST CIRCUITS AND WAVEFORMS

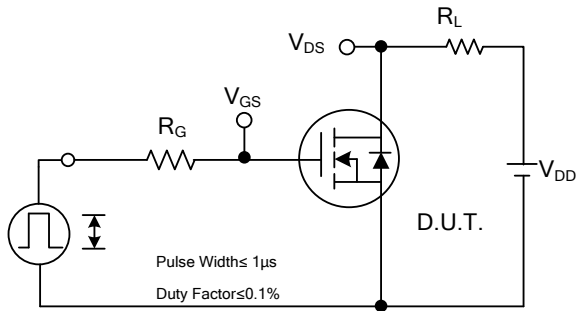


Peak Diode Recovery dv/dt Test Circuit

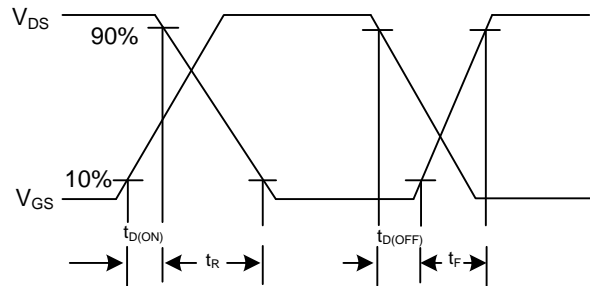


Peak Diode Recovery dv/dt Waveforms

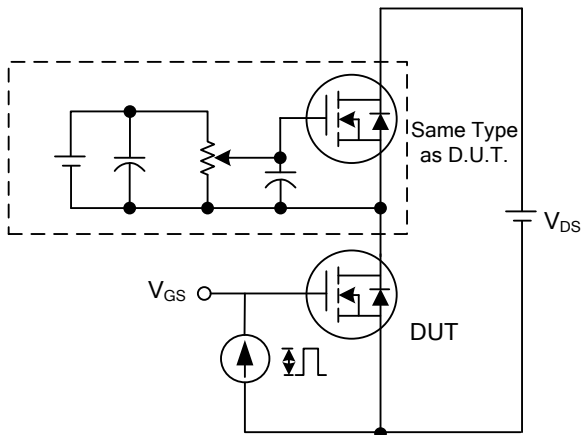
■ TEST CIRCUITS AND WAVEFORMS



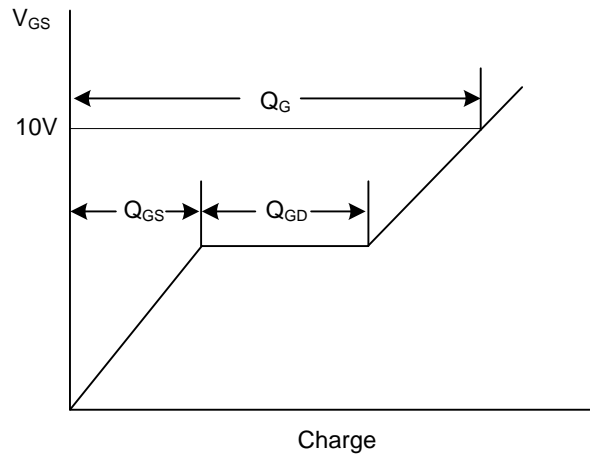
Switching Test Circuit



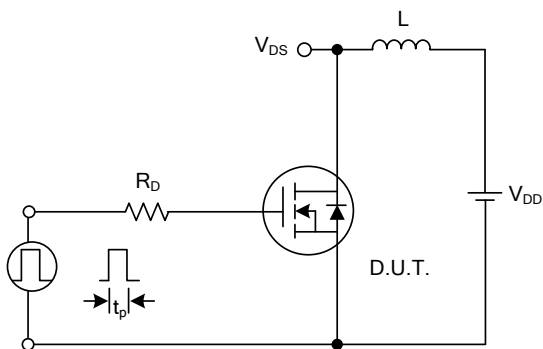
Switching Waveforms



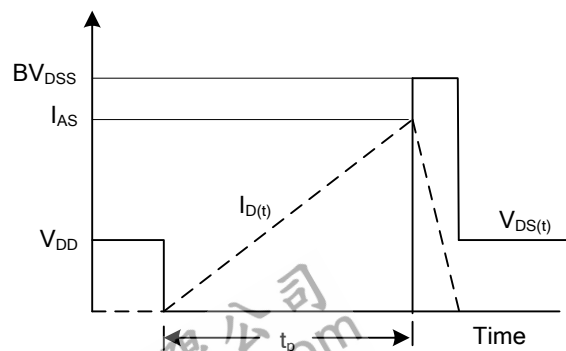
Gate Charge Test Circuit



Gate Charge Waveform

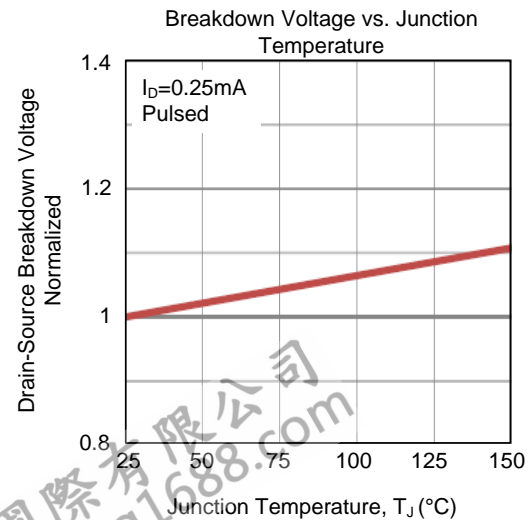
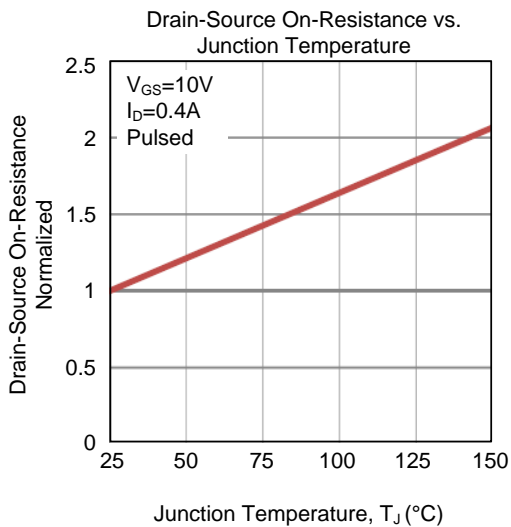
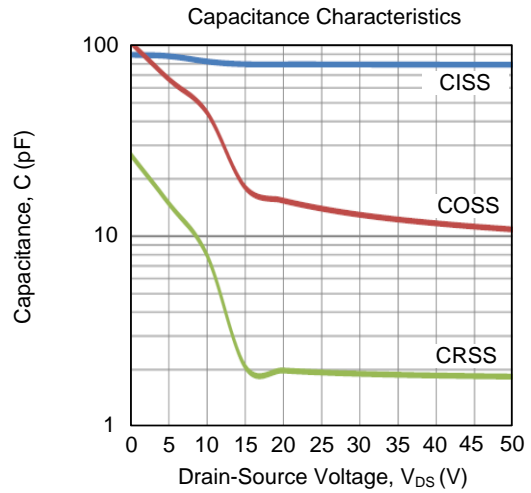
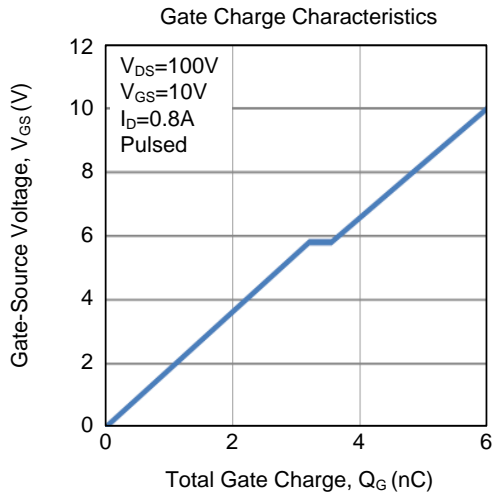
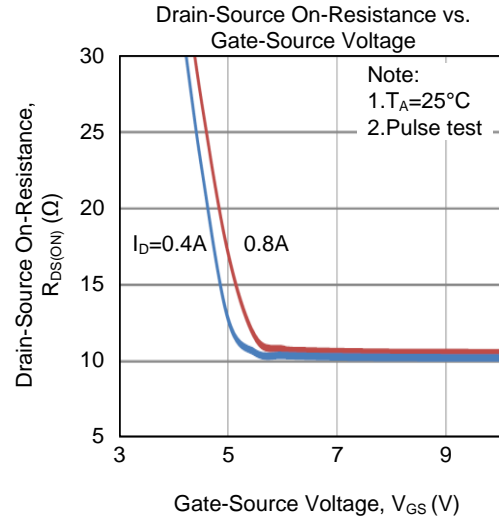
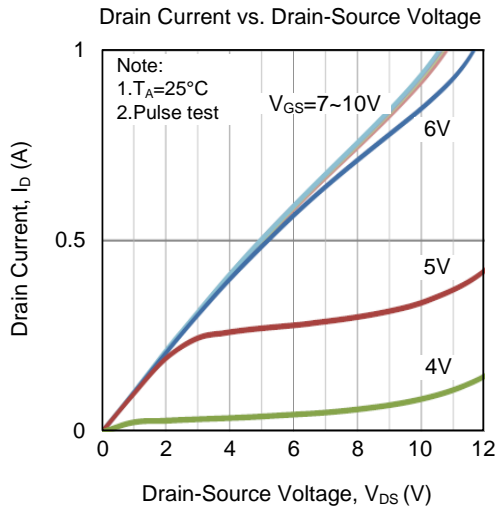


Unclamped Inductive Switching Test Circuit

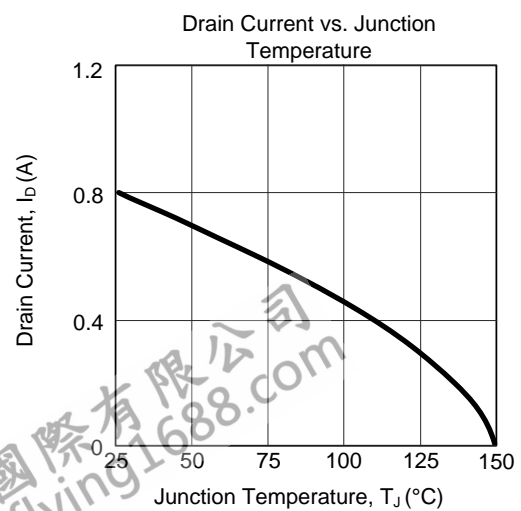
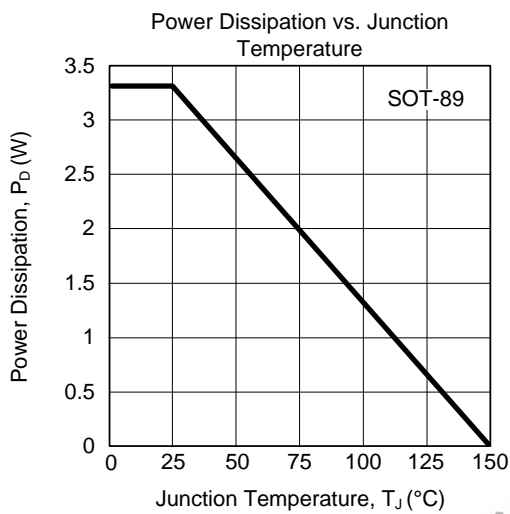
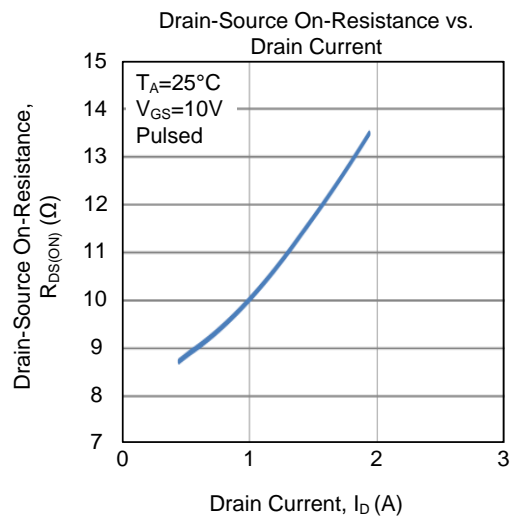
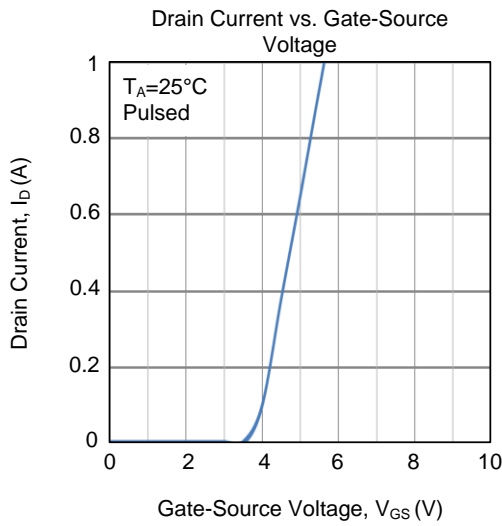
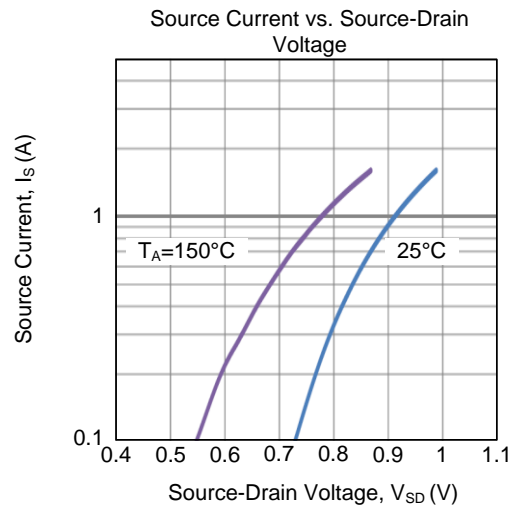
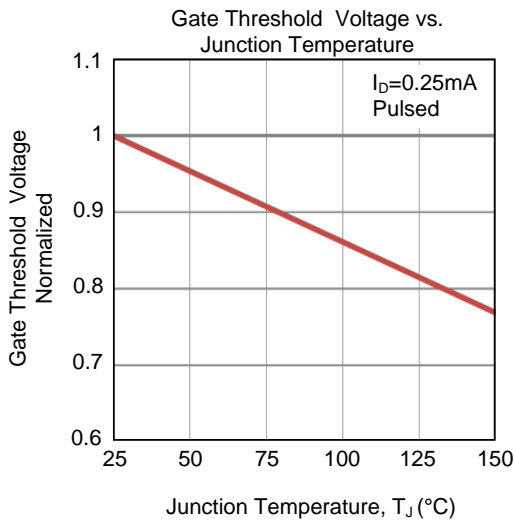


Unclamped Inductive Switching Waveforms

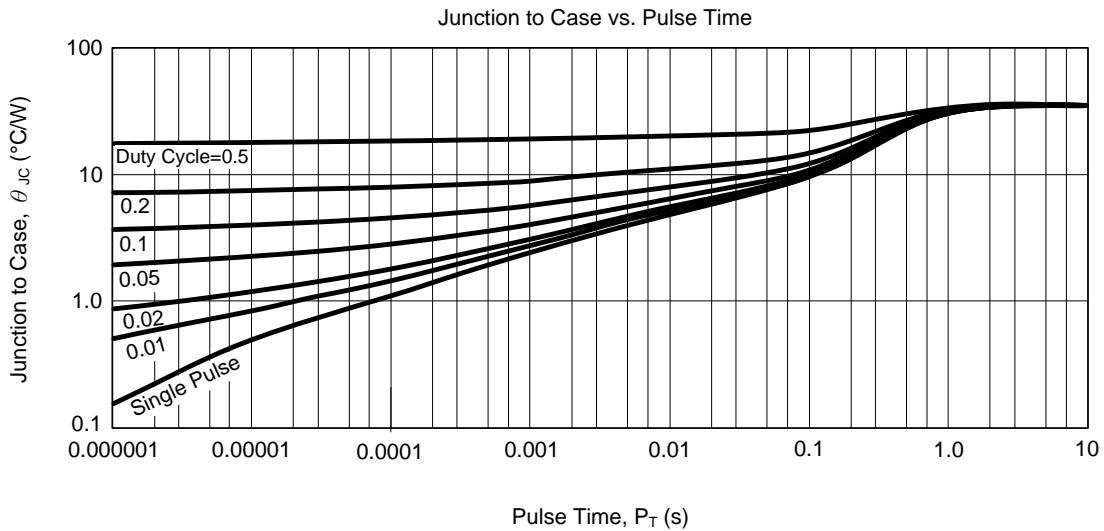
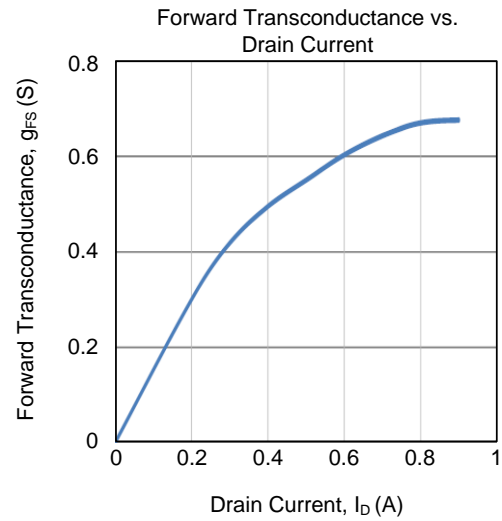
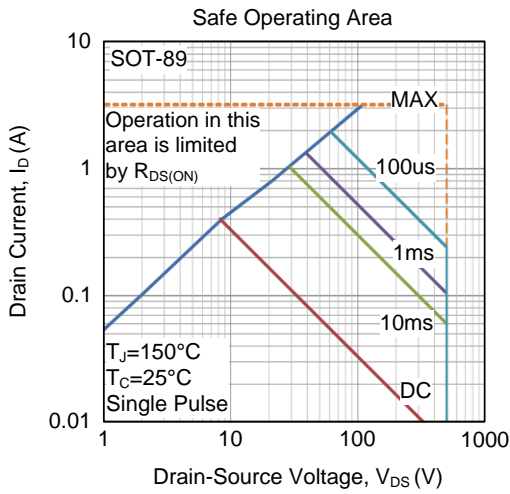
TYPICAL CHARACTERISTICS



■ TYPICAL CHARACTERISTICS (Cont.)



■ TYPICAL CHARACTERISTICS (Cont.)



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